

CAMJ Seminar

May 31, 2011

Comparison of Mechanical Properties of Pd coated Cu Wires

Dr. Wan Ho Song

Abstract

With the ever soaring price of Au, an alternative material such as Cu has been considered as bonding wire in the microelectronic packaging.

However, the Cu wire has some limitations such as oxidation, large hardness value, etc. that hinder its adaptation in the mainstream production. To overcome these limitations Pd has been introduced as coating for Cu wire. Recent result on the comparison study of Pd coated Cu wire will be presented following to a brief introduction to wire bonding technology.